

Title (en)
AN APPARATUS AND METHOD FOR THE MINIMIZATION OF UNDERCUT DURING A UBM ETCH PROCESS

Title (de)
VORRICHTUNG UND VERFAHREN ZUR MINIMIERUNG DER UNTERHÖHLUNG WÄHREND EINES UBM-ÄTZVERFAHRENS

Title (fr)
APPAREIL ET PROCÉDÉ DE RÉDUCTION AU MINIMUM DE GRAVURE SOUS-JACENTE LORS D'UN TRAITEMENT DE GRAVURE D'UBM

Publication
EP 4059047 A4 20240103 (EN)

Application
EP 20887509 A 20201102

Priority
• US 201916685640 A 20191115
• US 2020058479 W 20201102

Abstract (en)
[origin: WO2021096712A1] A plurality of endpoints in a wet etching process of a substrate are determined. A plurality of benchmark end points during a wet etching process of a first substrate are determined, using first light information represented by a HSV color model for sample locations of the first substrate. Etch parameters are generated for a wet etching process for a second substrate. The generated etch parameters are used with second light information represented by at least one value of the Hue, Saturation, Value color model associated with a plurality of sample locations of the second substrate to reach respective end points during the wet etching process of a second substrate.

IPC 8 full level
H01L 21/66 (2006.01); **H01L 21/67** (2006.01); **H01L 21/3213** (2006.01); **H01L 23/485** (2006.01)

CPC (source: EP)
H01L 21/67051 (2013.01); **H01L 21/67253** (2013.01); **H01L 22/26** (2013.01); **H01L 24/00** (2013.01); **H01L 21/32134** (2013.01); **H01L 2224/13** (2013.01)

Citation (search report)
• [IAY] US 2014242731 A1 20140828 - MAUER LAURA [US], et al
• [A] US 2018061032 A1 20180301 - BENVEGNU DOMINIC J [US]
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• See references of WO 2021096712A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
WO 2021096712 A1 20210520; EP 4059047 A1 20220921; EP 4059047 A4 20240103; TW 202135187 A 20210916

DOCDB simple family (application)
US 2020058479 W 20201102; EP 20887509 A 20201102; TW 109138896 A 20201106